

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	418	(324/601.ccls.) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/29 08:09
S2	114	(324/600.ccls.) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:03
S3	6	(("6348804") or ("5407752") or ("4858160")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/06/13 11:05
S4	2	("20040070405").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2004/12/22 10:30
S5	17	impedance adj standard adj substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/13 09:40
S6	14	S5 and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2004/12/22 13:27
S7	2	("4,697,143").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2004/12/22 11:22

S112	345	S111 and (substrate core) same (non\$1conduct\$5 dielectric insulat\$5 isolat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/15 12:46
S113	2	(bismaleimide adj triazine) same polyimide	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/15 14:42
S114	13	(bismaleimide adj triazine)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/15 14:48
S115	9	S114 and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/15 14:44
S116	4	S115 and polyimide	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/15 14:44
S117	160	((bismaleimide adj triazine) ("BT" adj resin)) near\$3 polyimide) same (non\$1conduct\$5 dielectric insulat\$5 isolat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/15 14:50
S118	6	((("5,578,932") or ("6,008,656") or ("5,587,934"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/09/23 14:35

S119	2	("5,034,708").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/09/23 15:14
S120	2	("6914436").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/09/23 15:14
S121	9	("20030115008" "20040100276" "5434511" "5467021" "5477137" "5537046" "5548221" "5552714" "5578932").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/26 13:30
S122	27734	((PCB PWB (print\$3 adj2 (board card slot substrate))) same (via (contact near3 (thru\$8 through)))) and @ad<"20030923"	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/27 09:11
S123	38	S122 and (oscill\$7 VNA (vector adj network adj anal\$5)) near3 calibrat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 08:41
S124	69	(contact near3 ((thru\$1 hole through\$1 hole ((thru\$8 through) adj hole)) adj via)) and @ad<"20030923"	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/26 16:00
S125	6	S124 and probe	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/26 16:02
S126	18	((((thru\$1 hole through\$1 hole ((thru\$8 through) adj hole)) adj via)) same probe) and @ad<"20030923"	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/27 08:40
S127	31862	(vias same probe) and @ad<"20030923"	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/27 08:40

S128	80	S127 and (oscill\$7 VNA (vector adj network adj anal\$5)) near3 calibrat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:19
S129	26	S128 and (PCB PWB (print\$3 adj2 (board card slot substrate)))	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/27 08:42
S130	139	((PCB PWB (print\$3 adj2 (board card slot substrate))) same (via same hole same probe)) and @ad<"20030923"	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/27 09:14
S131	1	S130 and (oscill\$7 VNA (vector adj network adj anal\$5)) with calibrat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 09:13
S132	11	(324/601.ccls.) and @ad<"20030923" and @pd>"20050607"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:09
S133	3	(324/130,202.ccls.) and @ad<"20030923" and @pd>"20050607"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:10
S134	6	(324/74,76,11.ccls.) and @ad<"20030923" and @pd>"20050607"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:10
S135	43	(324/754-758.ccls.) and @ad<"20030923" and @pd>"20050607"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:10

S136	42	(702/57,65,91,117,168.ccls.) and @ad<"20030923" and @pd>"20050607"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:10
S137	37	(324/158.1.ccls.) and @ad<"20030923" and @pd>"20050607"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:10
S138	2	(361/763,783.ccls.) and @ad<"20030923" and @pd>"20050607"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:10
S139	10	(361/792-795.ccls.) and @ad<"20030923" and @pd>"20050607"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:11
S140	1	(324/600.ccls.) and @ad<"20030923" and @pd>"20050607"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:09
S141	39	(174/259-261.ccls.) and @ad<"20030923" and @pd>"20050607"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:11
S142	76	(257/778-780.ccls.) and @ad<"20030923" and @pd>"20050607"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:11
S143	39	(324/754,755.ccls.) and @ad<"20030923" and @pd>"20050607"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:11

S144	492	(702/85.ccls.) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:19
S145	1428	(174/52.4.ccls.) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:19
S146	23	S144 and (oscill\$7 VNA (vector adj network adj anal\$5)) near3 calibrat\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 14:06
S147	16	(439/66.ccls.) and @ad<"20030923" and @pd>"20050607"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 13:35
S148	10	((oscill\$7 VNA (vector adj network adj anal\$5)) near3 calibrat\$5) and (((thru\$1hole through\$1hole ((thru\$8 through) adj hole)) adj via)) and probe and contact\$3 and first and second and (substrate core) and impedance and standard and (surface link connect\$3) and (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane circuit)) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 14:19
S149	0	((oscill\$7 VNA (vector adj network adj anal\$5)) near3 calibrat\$5) and (((thru\$1hole through\$1hole ((thru\$8 through) adj hole)) adj via)) and probe and contact\$3 and first and second and (substrate core) and impedance and standard and (surface link connect\$3) and (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane circuit)).clm.) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/27 14:18
S150	0	((impedance adj standard adj substrate) and (vector adj network adj analyzer) and (two adj probes) and (thru adj circuit) and (two adj contact)).clm.) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/29 08:21
S151	2	((impedance adj standard adj substrate) and (vector adj network adj analyzer) and (two adj probes) and (thru adj circuit) and (two adj contact)).clm.)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/29 08:21